

QFS-026-04.25-L-D-A THE PROPERTY OF timinaminativ QFS-032-04.25-L-D-DP-A QFS-026-04.25-L-D-A-GP

(0,635 mm) .025"

**QFS SERIES** 

## RUGGED GROUND PLANE SOCKET

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material: Liquid Crystal Polymer Contact & Ground Plane Material: Phosphor Bronze Plating: Au over 50μ" (1,27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Contact: 2.6 A per pin (1 pin powered per row) Ground Plane: 15.7 A per ground plane (1 ground plane powered)
Voltage Rating: 300 VAC mated with QMS

RoHS Compliant: Yes

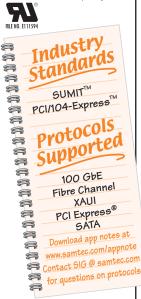
Operating Temp: -55°C to +125°C

Processing: Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (026-078) Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

## RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

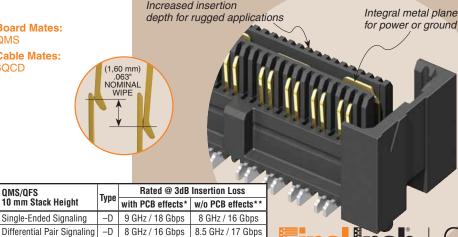


Note: Some lengths, styles and options are non-standard, non-returnable. **Board Mates:** 

Cable Mates: 6QCD

QMS/QFS

Differential Pair Signaling



ALSO **AVAILABLE** (MOQ Required)

- · Other platings
- Without PCB Alignment Pins
- Hot Pluggable
- 4 banks (104 -SE, 64 -DP) Contact Samtec.

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8 GHz / 16 Gbps		
8.5 GHz / 17 Gbps		
9 GHz / 18 Gbps		number
otimized PCB.		EIIUI

CERTIFIED

Gbps

available at www.samtec.com?QFS or contact sig@samtec.com PINS PER ROW QFS

NO. OF PAIRS

Performance data for other stack heights and complete test data

\*Performance data includes effects of a non-optimized PCB.

\*\*Test board losses de-embedded from performance data.

7.5 GHz / 15 Gbps

-DP

**LEAD** STYLE

LEAD

**STYLE** 

from

chart

**PLATING OPTION** 

**TYPE** 

OTHER OPTION

-026, –052, –078 (52 total pins per bank = -D)

-016, -032, -048 (16 pairs per bank = -D-DP)

MATED HEIGHT\* **QMS LEAD STYLE LEAD** Α STYLE -05.75 -06.75-09.75-04.25 (7,44) .293 10 mm 11 mm 14 mm **-06.25** (9,42) .371 12 mm 13 mm 16 mm

\*Processing conditions will affect mated height GP = No. of Banks x (21,34) .840 + (12,45) .490 No. of Banks x (21,34) .840 + (1,02) .040 → ← (21,34) .840 — (8, 13)320 (0.89).035 (1,02) .040 DIA →

(-04.25 lead style only) = 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

(-06.25 lead style only) = 10μ" (0,25 μm) Gold on Signal **Pins and Ground Plane** (Tin on Signal Pin tails, and Ground Plane tails)

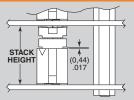


−D = Single-Ended

–D–DP = Differential Pair (-04.25 lead style only)

GP = Guide Holes ( -04.25 lead style only)

## **APPLICATION**



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated

INDUSTRY STANDARD	INTERCONNECTS				
	TERMINAL	SOCKET	BANKS	STACK HEIGHT	
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm	
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm	
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm	
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm	

Due to technical progress, all designs, specifications and components are subject to change without notice. ■ WWW.SAMTEC.COM I

-D-DP